

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 1, and add new claim 90 as follows:

Listing of Claims:

1. (Currently Amended) An integrated circuit package assembly for electrically isolating modules, comprising:

a substrate having a first side and an opposing second side;

a first module attached to the first side of the substrate;

a second module attached to the first side of the substrate;

~~the first conductive surface proximate to the second side of the substrate, the first conductive surface conductively coupled to the first module—the first module conductively coupled to the first conductive surface and isolated from the second conductive surface;~~ and

~~the second conductive surface spaced apart from the first conductive surface to form a capacitor with the first conductive surface, the second conductive surface being coupled to the second module—the second module conductively coupled to the second conductive surface and isolated from the first conductive surface.~~

2. (Previously Presented) The package assembly of claim 1, further comprising a dielectric interposed between the first and second conductive surfaces.

3. (Previously Presented) The package assembly of claim 1, further comprising an encapsulation substantially surrounding the package assembly.

4. (Previously Presented) The package assembly of claim 3 wherein the package assembly is encased in a polymer.

5. (Previously Presented) The package assembly of claim 3 wherein the package assembly is encased in ceramic.

6. (Previously Presented) The package assembly of claim 3 wherein the package assembly is encased in a glass.

7. (Previously Presented) The package assembly of claim 1 wherein the first module is an integrated circuit.

8. (Previously Presented) The package assembly of claim 7 wherein the integrated circuit is a physical layer chip.

9. (Previously Presented) The package assembly of claim 1 wherein the second module is an integrated circuit.

10. (Previously Presented) The package assembly of claim 9 wherein the integrated circuit is a link layer chip.

11. (Previously Presented) The package assembly of claim 1, further comprising a resistor having a first terminal coupled to the first conductive surface and further having a second terminal coupled to the second conductive surface.

12. (Previously Presented) The package assembly of claim 10 wherein the resistor has a resistance of approximately one megohm.

13. (Previously Presented) The package assembly of claim 11 wherein the resistor is a resistant film.

14. (Previously Presented) The package assembly of claim 1, further comprising a first ground plane connected to the first conductive surface, and a second ground plane connected to the second conductive surface.

15. (Previously Presented) The package assembly of claim 13 wherein the first ground plane comprises a ground wire of a cable bus.

16. (Previously Presented) The package assembly of claim 13 wherein the second ground plane comprises a chassis of a computer.

17-89. (Canceled)

90. (New) An integrated circuit package assembly for electrically isolating modules, comprising:

- a substrate having a first side and an opposing second side;
- a first integrated circuit module attached to the first side of the substrate;
- a second integrated circuit module attached to the first side of the substrate;
- a first conductive surface attached to the second side of the substrate, the first conductive surface conductively coupled to the first module; and
- a second conductive surface spaced apart from the first conductive surface to form a capacitor with the first conductive surface, the second conductive surface being coupled to the second module; and
- a dielectric interposed between the first and second conductive surfaces.